



2-26-04

PATENT

Attorney Docket No.: 007685/PMG/EPIC/JW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:) Group Art Unit: 2818
Judon Tony PAN) Examiner: unknown at this time
Serial No.: 10/654,240)
Confirmation No.: 4883)
Filed: 09/02/2003)
For: Bond Pad Techniques For Integrated) PATENT COUNSEL
Circuits) APPLIED MATERIALS, INC.
) Legal Affairs Department
) P.O. Box 450 A
) Santa Clara, CA 95052

MS Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

INFORMATION DISCLOSURE STATEMENT TRANSMITTAL

Enclosed for the above-identified patent application please find:

- Information Disclosure Statement
- Form PTO-1449
- Copy of 24 reference publications

Respectfully submitted,

Dated: Feb. 25, 2004

By: Albert J. Dalhuisen
Albert J. Dalhuisen
Reg. No.: 36,117

I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope to: MS Patent Application, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

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Date of Deposit Feb. 25, 2004

Signature Albert J. Dalhuisen
Albert J. Dalhuisen



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Serial No.: 10/654,240

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For: Bond Pad Techniques For
Integrated Circuits

) Group Art Unit: 2818

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) **INFORMATION DISCLOSURE STATEMENT**

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MS Patent Application
Commissioner for Patents
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Sir:

This Information Disclosure Statement

- ☒ [X] is filed within three months after the filing date of a national application or three months after the date of entry of the national stage in an international application or before the mailing date of a first office action on the merits, whichever occurs last. 37 C.F.R. § 1.97(b).
- ☐ [] is filed **before** the mailing date of either (a) a final action under § 1.113 or (b) a notice of allowance under § 1.311, whichever occurs first, and is accompanied by ___ certification as specified in § 1.97(e) or ___ the fee set forth in § 1.17(p). 37 C.F.R. § 1.97(c).
- ☐ [] is filed **after** the mailing date of either (a) a final action under § 1.113 or (b) a notice of allowance under § 1.311, whichever occurs first, but before the payment of the issue fee, and is accompanied by

- ☐ certification as specified in § 1.97(e) **and**
☐ the fee set forth in 37 C.F.R. § 1.17(p)

Applicant submits herewith patent(s), publication(s), or other information of which applicant is aware, which applicant believes may be material to the examination of this application and in respect of which there may be a duty to disclose. The filing of this information disclosure statement shall not be construed as a representation that a search has been made (37 C.F.R. 1.97(g)), an admission that the information cited is, or considered to be, material to patentability or that no other material information exists. The filing of this information disclosure statement shall not be construed as an admission against interest in any manner. Notice of January 9, 1992, 1135 O.G. 13-25, at 25. Each reference is identified on the attached Form PTO-1449. A copy of each of the references is supplied herewith.

A concise explanation of the items listed on PTO-1449 is:

- ☒ [X] not given, since all items are in the English language
☐ [] given for only some listed non-English language item(s)
☐ [] given for each listed item, since all are non-English language documents

The following printed publications are referred to in the body of the specification:

U.S. Pat. Application No.: 09/553,461, Filing Date 4/19/02, to Huang et al., Assignee:
Applied Materials, Inc. Santa Clara, California

U.S. Pat. No:
6,072,227, to Yau et al., 6/6/00
6,054,379, to Yau et al., 4/25/00

Applicant has become aware of the following printed publications which may be material to the examination of this application:

U.S. Patent Application Publication No.:
2002/0096764, to Huang, 7/25/2002
2002/0005292, to Kaneda et al., 1/17/2002
2001/0033031, to Shibata, 10/25/2001
2001/0017221, to Horiuchi et al., 8/30/2001
2001/0013650, to Goetz et al., 8/16/2001

U.S. Patent No.:
6,452,271, to Jiang et al., 9/17/2002
6,445,069, to Ling et al., 9/3/2002
6,444,489, to Lin, 9/3/2002
6,424,036, to Okada, 7/23/2002
6,362,090, to Paik et al., 5/26/2002



6,153,940, to Zakel et al., 11/28/2000
5,891,756, to Erickson, 4/6/1999
5,886,877, to Shingai et al., 3/23/1999
5,821,626, to Ouchi et al., 10/13/1998
5,290,732, to Kumar et al., 3/1/1994
5,192,835, to Bull et al., 3/9/1993
5,134,460, to Brady et al., 7/28/1992
4,661,375, to Thomas, 4/28/1987
3,986,255, to Mandal, 10/19/1976

Other documents:


Charles A. Harper, Ed., Electronic Packaging And Interconnection Handbook, 3rd ed., McGraw-Hill, pp.7.87 & 7.88, 2000

George G. Harman et al., "Wire Bonding To Advanced Copper-Low-K Integrated Circuits, the Metal/Dielectric Stacks, and Materials Considerations", To be published in International Microelectronics Symposium (IMAPS), Baltimore, MD, 8 pages, Oct. 9-12, 2001.

Applicant respectfully submits that the invention claimed in the above-identified application is patentable over the references known to applicant and disclosed herein.

Respectfully submitted,

Dated: Feb. 25, 2004

By: 
Albert J. Dalhuisen
Reg. No.: 36,117

FORM PTO-1449
(Modified)

U.S. Department of Commerce
Patent and Trademark Office

007685/PMG/EPIC/JW
Attorney Docket No.:

Serial No.: 10/654,240

INFORMATION DISCLOSURE STATEMENT BY APPLICANT
(Use Several Sheets If Necessary)

Applicant Judon Tony PAN:

(37 CFR § 1.98(b))

Filing Date: 09/02/2003

Group: 2818

U.S. PATENT DOCUMENTS

Examiner Initials	Serial/Patent Number	Issue Date	Applicant/Patentee	Class	Subclass	Filing Date
AA	U.S. 09/553,461		Huang et al.			4/19/00
AB	6,452,271	9/17/02	Jiang et al.	257	750	7/31/98
AC	6,445,069	9/3/02	Ling et al.	257	738	1/22/01
AD	6,444,489	9/3/02	Lin	438	107	12/15/00
AE	2002/0096764	7/25/02	Huang			1/19/01
AF	6,424,036	7/23/02	Okada	257	734	9/16/99
AG	6,362,090	3/26/02	Paik et al.	438	614	11/3/00
AH	2002/0005292	1/17/02	Kaneda et al.			7/2/01
AI	2001/0033031	10/25/01	Shibata			3/22/01
AJ	2001/0017221	8/30/01	Horiuchi et al.			2/24/01
AK	2001/0013650	8/16/01	Goetz et al.			12/20/00
AL	6,153,940	11/28/00	Zakel et al.	257	779	11/10/95
AM	6,072,227	6/6/00	Yau et al.	257	642	7/13/98
AN	6,054,379	4/25/00	Yau et al.	438	623	2/11/98
AO	5,891,756	4/6/99	Erickson	438	108	6/27/97
AP	5,886,877	2/23/99	Shingai et al.	361	768	10/9/96
AQ	5,821,626	10/13/98	Ouchi et al.	257	778	6/25/96
AR	5,290,732	3/1/94	Kumar et al.	437	183	6/9/92
AS	5,192,835	3/9/93	Bull et al.	174	260	10/9/90
AT	5,134,460	7/28/92	Brady et al.	357	71	11/2/90
AU	4,661,375	4/28/87	Thomas	427	89	3/7/86
AV	3,986,255	10/19/76	Mandal	29	626	11/29/74

OTHER DOCUMENTS (including Author, Title, Date, Relevant Pages, Place of Publication)

AW	Charles A. Harper, Ed., <u>Electronic Packaging And Interconnection Handbook</u> , 3 rd ed., McGraw-Hill, New York, pp. 7.87 & 7.88, 2000
AX	George G. Harman et al., "Wire Bonding To Advanced Copper-Low-K Integrated Circuits, the Metal/Dielectric Stacks, and Materials Considerations", To be published in International Microelectronics Symposium (IMAPS), Baltimore, MD, 8 pages, Oct. 9-12, 2001

Examiner:

Date Considered:

EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.